## / Descriptions

1.0A ABF
1.0A Surface Mount Glass Passivated Bridge Rectifier, ABF thin package.

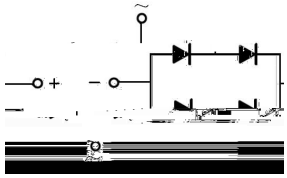
## / Features

1000V 1.0A
Glass Passivated Chip Junction,Reverse Voltage: 1000V,Forward Current:1.0A, Fast reverse recovery time,Designed for Surface Mount Application.Halogen free product.

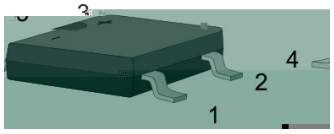
## / Applications

.
General purpose.

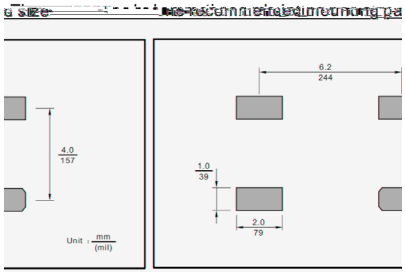
## / Equivalent Circuit



## / Pinning




| PIN | DESCRIPTION |
|---|---|
| 1 | Input Pin ( ~ ) |
| 2 | Input Pin ( ~ ) |
| 3 | Output Anode ( + ) |
| 3 | Output Anode |




## / Marking

See Marking Instructions.

## / Absolute Maximum Ratings(Ta=25 )

| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Maximum Repetitive Peak Reverse Voltage | $V_{RRM}$ | 1000 | V |
| Maximum RMS Voltage | $V_{RMS}$ | 700 | V |
| Maximum DC Blocking Voltage | $V_{DC}$ | 1000 | V |
| Average Rectified Output Current at $T_c$ = 125 | $I_o$ | 1.0 | A |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load | $I_{FSM}$ | 30 | A |
| Typical Junction Capacitance Note1 | $C_j$ | 30 | pF |
| Typical Thermal Resistance Note2 | $R_{\theta JA}$ | 75 | /W |
| Operating and Storage Temperature Range | $T_j$,$T_{stg}$ | -55~150 | |

Note:

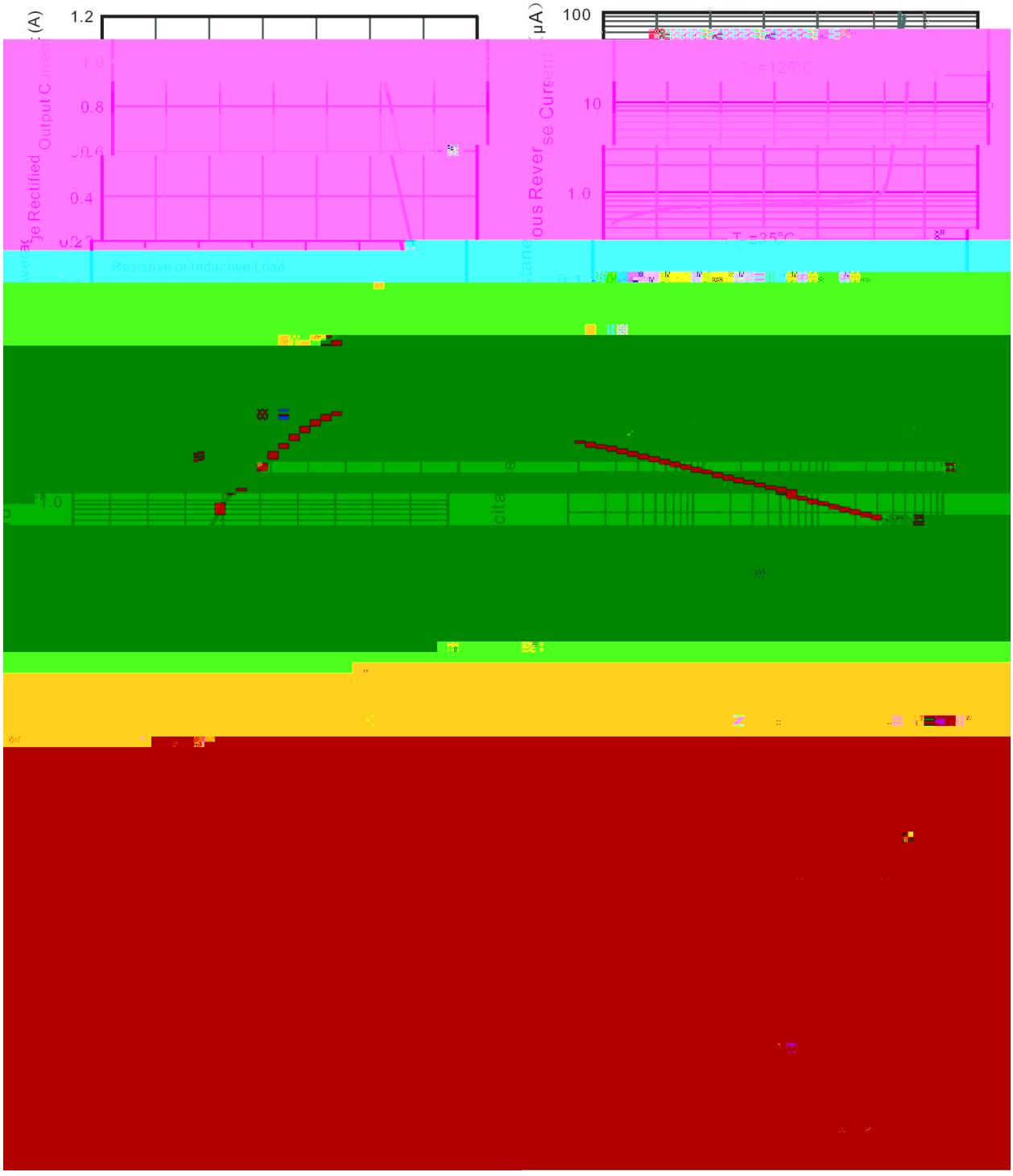
1.Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4 1.0" X 1.0" (2.54 X 2.54 cm) copper pad.

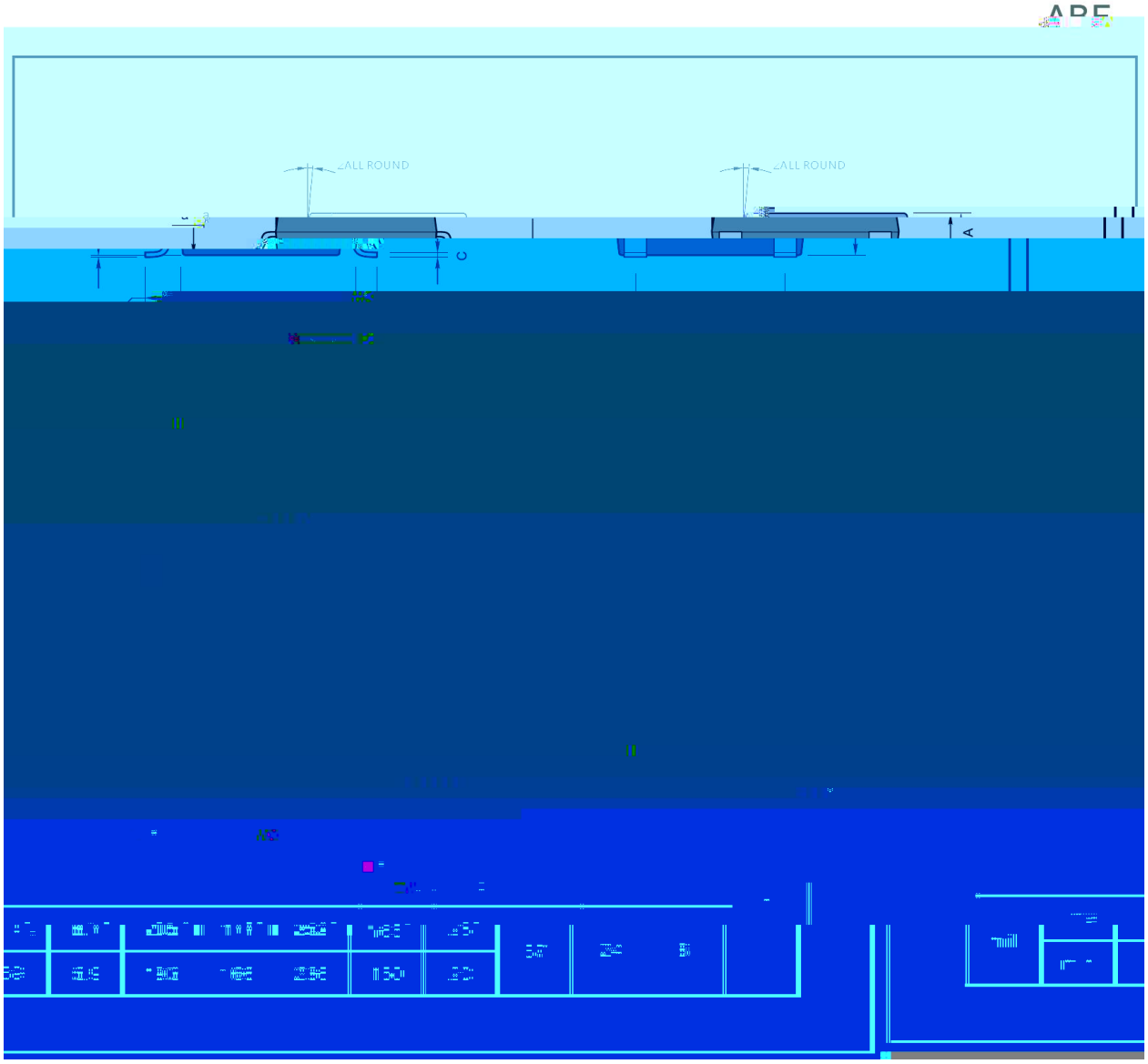
## / Electrical Characteristics(Ta=25 )

| Parameter | Symbol | Test Conditions | Rating | Unit |
|---|---|---|---|---|
| Forward Voltage per element | $V_F$ | $I_F$=1.0A | 1.3 | V |
| Maximum DC Reverse Current at Maximum DC Blocking Voltage | $I_R$ | $T_a$=25 | 5.0 | μA |
| | | $T_a$=125 | 50 | μA |
| Maximum Reverse Recovery Time | $t_{rr}$ | $I_F$ =0.5A $I_R$=1.0A $I_{rr}$=0.25A | 200 | ns |

## / Electrical Characteristic Curve

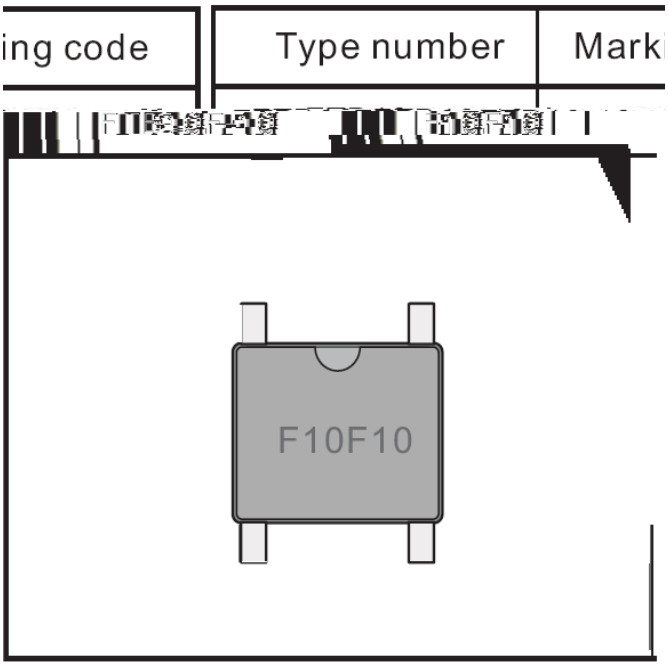


## / Package Dimensions



## / Marking Instructions

Marking

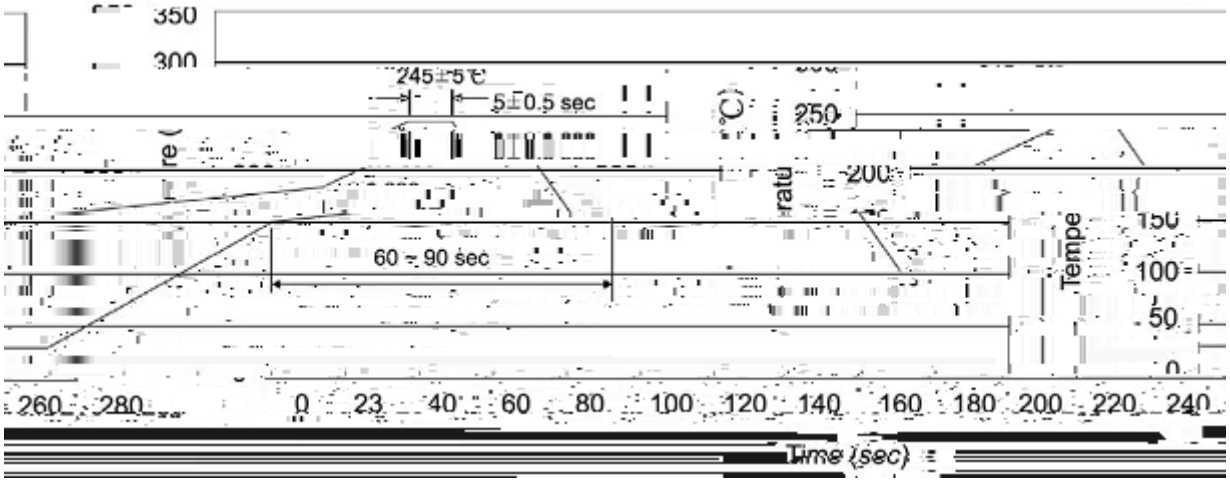


## / Marking Instructions

F10F10
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## ( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)




Note:

1 25 150 60 90sec;

1.Preheating:25~150 , Time:60~90sec.

2 245±5 5±0.5sec;

2.Peak Temp.:245±5 , Duration:5±0.5sec.

3 2 10 /sec.

3. Cooling Speed: 2~10 /sec.

## / Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

## / Packaging SPEC.

/ REEL

| Package Type | Units | | | | | Dimension | | (unit mm$^3$) |
|---|---|---|---|---|---|---|---|---|
| | Units/Reel / | Reels/Inner Box / | Units/Inner Box / | Inner Boxes/Outer Box / | Units/Outer Box / | Reel | Inner Box | Outer Box |
| ABF | 5000 | 2 | 10000 | 5 | 50000 | 13 ×15 | 336X336X40 | 380X335X366 |

## / Notices